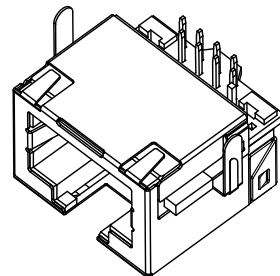
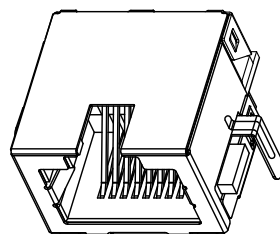
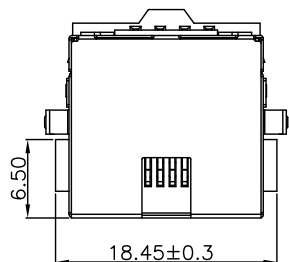


RoHS compliant



NOTES:

1. HOUSING MATERIAL: GLASS FILLED POLYESTER UL94V-0.
2. CONTACT MATERIAL: COPPER ALLOY, T=0.35.
3. PLATING: GOLD PLATED ON CONTACT AREA, 100u" MIN. MATTE TIN PLATED ON SOLDERING AREA, 50u" MIN. NICKEL PLATED OVERALL.
4. SHELL: COPPER ALLOY, T=0.20. 30u" MIN. NICKEL PLATED OVERALL.

ELECTRICAL:

1. VOLTAGE RATING: 125V AC RMS.
2. CURRENT RATING: 1.5AMP.
3. CONTACT RESISTANCE: 40MILLIOHMS MAX.
4. INSULATION RESISTANCE: 500MEGOHMS MIN @100V DC.

MECHANICAL:

1. DURABILITY: 750 CYCLES MIN.
2. INSERTION FORCE: 22N MAX.
3. REMOVAL FORCE (WITHOUT PLUG LOCK): 22N MAX.

ENVIRONMENTAL:

1. STORAGE: -40°C~85°C
2. OPERATION: 0°C~70°C

*Apply to the EU standards (ROSH)

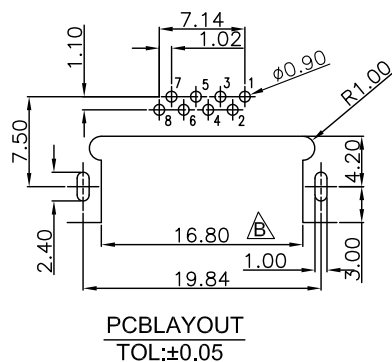
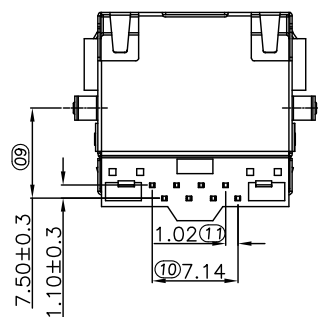
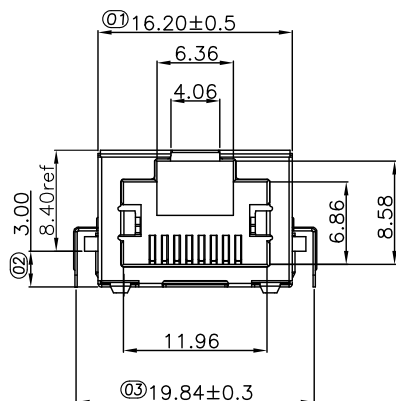
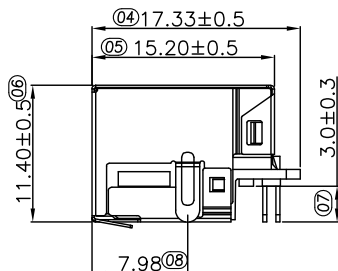
1. ⑦~⑪为QIP尺寸.

P/N: RJ58D-8811-101415P

RJ45 SINK DIP SERIES PCB JACK

POSITIONS (金针位置):
8-POSITIONS (8P)
CONTACTS (金针根数):
8-CONTACTS (8C)
PORTS (窗口):
11-1X1
SHIELD (屏蔽壳):
1-WITH SHIELD (有屏蔽壳)
LED STYLE (LED 颜色类型):
0-Without LED (无LED)

PACKING TYPE (包装):
R-REEL (卷带包装)
P-PVC TRAY (盘装)
HEIGHT (沉板高度):
5-SINK H=3.0 (沉板3.0)
COLOR (颜色):
1-BLACK (黑色)
PLASTIC (塑料):
4-LCP
GOLD PLATING (镀金厚度):
1-1U"; 2-1.5U"; 3-3U"; 4-6U";
5-15U"; 6-30U"; 7-50U";



					GENERAL TOLERANCE		DRAWN		Gene Li		2017/08/11		X-SHUN 东莞市祥舜电子科技有限公司 DONGGUAN X-SHUN ELECTRONIC TECHNOLOGY CO., LTD							
					.X	±0.35	X.°	± 2°	CHECKE		LM			PART NO.		RJ58D-8811-101415P				
A0		NEW DESIGN		2017/08/11	.XX	±0.25	X°	± 1°	APPROVE					TITLE:		RJ45 8P8C DIP SINK H=3.0MM W/SHIELD				
REV	ECN NO	DESCRIPTION		DATE	SIGNATURE	PROJECT				UNIT	mm	SCALE	1:1	SHEET	1/1	REV	A0	DRAWING NO.	RJ58D-88	